ROHS

LEADER TIME SRL

PRODUCT SPECIFICATION

16*2 Characters COB LCD MODULE MODEL: LT-1602L-902 Ver:1.0

< > > Finally Specification

CUSTOMER'S APPROVAL						
CUSTOMER:						
SIGNATURE: DATE:						

APPROVED	РМ	PD	PREPARED
BY	REVIEWD	REVIEWD	Ву

Prepared By: LEADER TIME SRL

VIA MONS. PROSDOCIMI, 27 36042 BREGANZE (VI)

• This specification is subject to change without notice. Please contact LT or it's representative before designing your product based on this specification.

1/1

Issued Date: 2011.05.26

Doc. No.:

Revision Status

Version	Revise Date	Page	Content	Modified By
VER 1.0	2011.05.26		First Issued	

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1. Features

The features of LCD are showed as follows

* Display mode : FSTN/Transmissive/Negative * Controller IC : AIP31066(English-Japanese)

* Display format : 16X2Characters * Interface Input Data : 8 bit or 4 bit MPU * Driving Method : 1/16Duty, 1/5Bias

* Viewing Direction :12 O'clock

* Backlight : LED Unit /White (side)

*Sample NO. : EC1602K3FVW7B-B0 01/20110526

2. MECHANICAL SPECIFICATIONS

Item	Specification	Unit
Module Size	85(W) x36(H) x9.5MAX(T)	mm
Viewing Area	64.5(W) x 16(H)	mm
Activity Display Area	56.21(W)x11.5(H)	mm
Character Font	5x8 Dots	-
Character Size	2.96(W)x5.56(H)	mm
Character Pitch	3.55(W)x5.94(H)	mm
Dot Size	0.56(W)x0.66(H)	mm

3. ELECTRICAL SPECIFICATIONS

3-1 ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C)

Item	Symbol	Min	Max	Unit
Supply Voltage For Logic	Vdd	0.3	7.0	V
Supply Voltage For LCD Drive	V_{LCD}	VDD-15	VDD+0.3	V
Input Voltage	Vin	-0.3	VDD+0.3	V
Operating Temp.	Тор	-20	+70	°C
Storage Temp.	Tst	-30	+80	°C

^{*.} NOTE: The response time will be extremely slow when the operating temperature is around -10°C, and the back ground will become darker at high temperature operating.

3-2 ELECTICAL CHARACTERISTICS

Item		Symbol	Test Condition	Min.	Тур.	Max.	Unit	
Logic supply Voltage		V _{DD} – V _{ss}		4.5	5	5.5	\ \	
LCD Dri	LCD Drive		Ta = 25 °C	3.5	3.8	4.1	V	
Input Voltage	"H" Level	V _{IH}	VDD=5V ± 10%	\/ 5 \/ + 400/	2.2	-	Vdd	V
	"L" Level	V _{IL}		-0.3	-	0.6	V	
Frame Frequency		f _{FLM}		-	-	84.4	Hz	
Current Cons	umption	I _{DD}		-	1.35	-	mA	

3-3 BACKLIGHT

3-3-1. Absolute Maximum Ratings

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Current	IF		-	-	30	mA
Reverse Voltage	VR	Ta = 25 °C	-	-	5	V
Power Dissipation	PD		-	-	93	mW

3-3-2. Electrical-optical Characteristics

Item	Symbol	Condition	Mi	n.	Тур		Ma	ax.	Unit
Forward Voltage	VF		-	-	3.	.1	-	-	V
Average Luminous Intensity	Iv If=30mA Ta = 25 °C		150		-		-		cd/m ²
Color Coordinates	_	1a = 25 C	X	Y	X	Y	Х	Υ	_
Color Coordinates			0.25	0.25	0.28	0.28	0.31	0.31	-

The brightness is measured without LCD panel

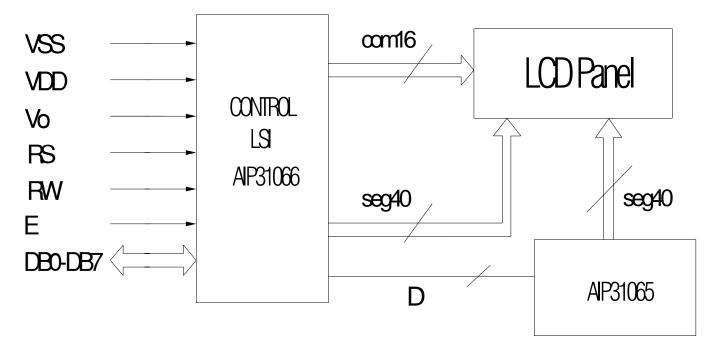
For operation above 25 °C,The Ifm & Pd must be derated, the current derating is -0.36mA/ °C for DC drive and -0.86mA/ °C for Pulse drive, the Power dissipation is -0.75mW/ °C.The product working current must not more than the 60% of the Ifm or Ifp according to the working temperature.

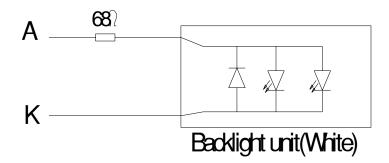
4. TERMINAL FUNCTIONS AND BLOCK DIAGRAM

4-1 INTERFACE PIN FUNCTION DESCRIPTION

PIN NO.	SYMBOL	FUNCIONS
1	VSS	Ground
2	VDD	Supply voltage for logical circuit
3	V0	Supply voltage for LCD driving
4	RS	A signal for selecting registers. 1: Data Register (for read and write) 0: Instruction Register (for write)
5	R/W	A signal for selecting read or write actions.1: Read, 0: Write.
6	E	A enable signal for reading or writing data.
7-14	DB0~DB7	8 Bit Data Bus
15	Α	Backlight (5.0V)
16	K	Backlight (-)

4-2 BLOCK DIAGRAM



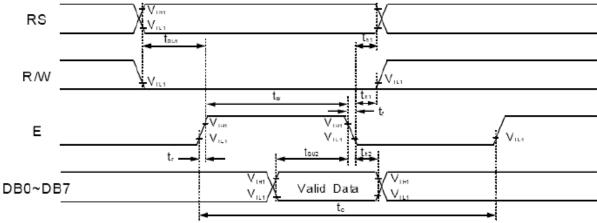


5. TIMING CHARACTERISTICS

5 - 1 Write mode

Mode	Characteristic	Symbol	Min.	Тур.	Max.	Unit
Write Mode (Refer to Fig-1)	E Cycle Time	tc	500	-	-	
	E Rise / Fall Time	t _R ,t _F	-	-	20	
	E Pulse Width (High, Low)	t _w	230	-	-	
	R/W and RS Setup Time	t _{su1}	40	-	-	ns
	R/W and RS Hold Time	t _{H1}	10	-	-	
	Data Setup Time	t _{su2}	80	-	-	
	Data Hold Time	t _{H2}	10	-	-	

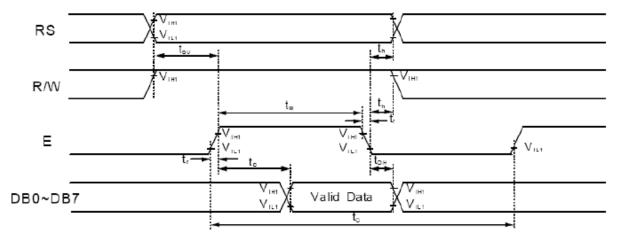
5-2 Write mode timing diagram



5.3 Read mode

Read Mode (Refer to Fig-2)	E Cycle Time	tc	500	-	-	
	E Rise / Fall Time	t _R , t _F	-	-	20	
	E Pulse Width (High, Low)	t _w	230	-	-	
	R/W and RS Setup Time	t _{su}	40	-	-	ns
	R/W and RS Hold Time	t _H	10	-	-	
	Data Output Delay Time	t _D	-	-	120	
	Data Hold Time	t _{DH}	5	-	-	

5-4Read mode timing diagram



6. COMMAND LIST

Instruction				Inst	ructi	on C	ode				Description	Execution time (fosc=
instruction .	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Description	270 kHz)
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "20H" to DDRAM and set DDRAM address to "00H" from AC	1.53 ms
Return Home	0	0	0	0	0	0	0	0	1	-	Set DDRAM address to '00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.	1.53 ms
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	SH	Assign cursor moving direction and enable the shift of entire display.	39 μs
Display ON/ OFF Control	0	0	0	0	0	0	1	D	С	В	Set display(D), cursor(C), and blinking of cursor(B) on/off control bit.	39 µs
Cursor or Display Shift	0	0	0	0	0	1	s/c	R/L	-	-	Set cursor moving and display shift control bit, and the direction, without changing of DDRAM data.	39 µs
Function Set	0	0	0	0	1	DL	N	F	-	-	Set interface data length (DL: 8-bit/4-bit), numbers of display line (N: 2-line/1-line) and, display font type (F:5×11dots/5×8 dots)	39 µs
Set CGRAM Address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	Set CGRAM address in address counter.	39 µs
Set DDRAM Address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Set DDRAM address in address counter.	39 µs
Read Busy Flag and Address	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0 μs
Write Data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM/CGRAM).	43 μs
Read Data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM (DDRAM/CGRAM).	43 μs

^{* &}quot;-": dont care

NOTE: When an MPU program with checking the Busy Flag(DB7) is made, it must be necessary 1/2Fosc is necessary for executing the next instruction by the falling edge of the 'E' signal after the Busy Flag (DB7) goes to "Low".

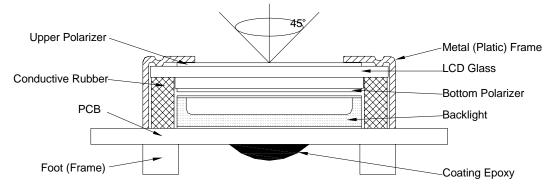
7. CHARACTER GENERATOR ROM

Upp er 4 Lewer Bits 4 Bib		0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1 101	11 10	1111
xxxx00000	RAM (1)			0	9	P	•	F				_	9	Ę	Ċζ	þ
xxxx0001	(2)		!	1	A	Q	a	9				7	Ŧ	4	ä	q
xxxx0010	(3)		Ш	2	В	R	b	٣			Γ	1	ŋ	X	ß	0
xxxx0011	(4)		#	3	C	5	C	s			L	Ċ	Ť	ŧ	ε	600
xxxx0100	(5)		\$	4	D	Ţ	d	ţ,			٠.	I	ŀ	þ	μ	Ω
xxxx0101	(6)		7	5	E	U	e	u			•	7	†	1	σ	ü
xxxx0110	(7)		&	6	F	Ų	f	Ų			7	Ħ	~	3	ρ	Σ
xxxx0111	(8)		7	7	G	W	9	W			7	‡	Z	Ŧ	9	π
xxxx1000	(1)		(8	H	X	h	X			4	7	*	IJ	Ţ	X
xxxx1001	(2)		ን	9	Ι	Y	i	y			Ċ	ጎ	Į	ιb	-1	4
xxxx1010	(3)		*	•	J	Z	j	Z			I	J	n	ŀ	j	Ŧ
xxxx1011	(4)		+	;	K		k	{			#	Ħ	t		×	F
xxxx1100	(5)		7	<	L	¥	1				ħ	Ð	7	7	¢	Ħ
xxxx1101	(6)		_	=	M]	M	}			ュ	Z	^	_,	Ł	÷
xxxx1110	(7)		•	>	N	^	n	÷			3	t	#	**	ħ	
xxxx1111	(8)		/	?	0	_	0	+			'n	y	7	•	ö	

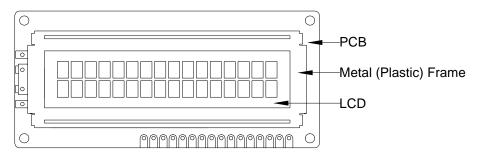
Note: The user can specify any pattern for character-generator RAM.

8. QUALITY SPECIFICATIONS

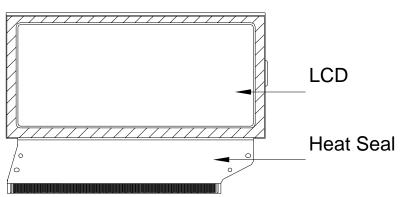
- 8 1. LCM Appearance and Electric inspection Condition
- 1. Inspection will be done by placing LCM 30cm away from inspector's eyeballs under normal illumination.



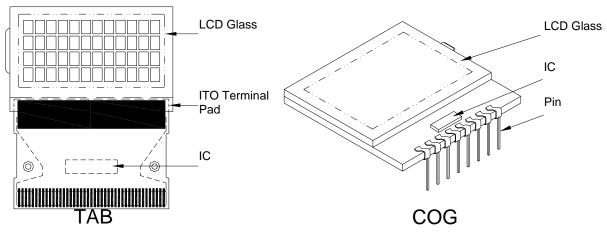
- 2. View Angle: with in 45° around perpendicular line.
- 8-2. Definition
- **1. COB**



2. Heat Seal



3. TAB and COG



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8-3. Sampling Plan and Acceptance

1.Sampling Plan

MIL - STD - 105E (||) ordinary single inspection is used.

2.Acceptance

Major defect: AQL = 0.65%Minor defect: AQL = 1.5%

8-4. Criteria

1.COB

Defect	Inspection Item	Inspection Standards				
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm ²	Reject			
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject			
Major Void or hole of coating epoxy		Expose bonding wire or IC	Reject			
Major	PCB cutting defect	Exceed the dimension of drawing	Reject			

2.SMT

Defect	Inspection Item	Inspection Standa	ards
Minor	Component marking not readable		Reject
Minor	Component height	Exceed the dimension Of drawing	Reject
Major	Component solder defect (missing, extra, wrong component or wrong orientation		Reject
Minor	Component position shift component soldering pad	X < 3/4Z Y > 1/3D	Reject
Minor	Component tilt component soldering pad	Y > 1/3D	Reject
Minor	Insufficient solder component PAD	<i>θ</i> ≤ 20°	Reject

3. Metal (Plastic) Frame

Defect	Inspection Item	lı	nspection Standa	rds		
Major	Crack / breakage	Any	/where	Reject		
		W	L	Acceptable of Scratch		
		w<0.1mm	Any	Ignore		
		0.1 <u><</u> w<0.2mm	L <u><</u> 5.0mm	2		
Minor	Frame Scratch	0.2 <u><</u> w<0.3mm	L <u><</u> 3.0mm	1		
- 		w <u>></u> 0.3mm	Any	0		
		Note: 1. Above criteria applicable to scratch line with distance greater than 5mm. 2. Scratch on the back side of frame (no visible) can be ignored.				
				Acceptable of Dents / Pricks		
		Φ<	2			
	Frame Dent , Prick	1.0<	1			
Minor	$\Phi = \frac{L + W}{2}$	1.5	0			
	2	Note: 1. Above criteria applicable to any two dents / pricks with distance greater than 5mm 2. Dent / prick on the back side of frame (not visible) can be ignored				
Minor	Frame Deformation	Exceed the dimension of drawing				
Minor	Metal Frame Oxidation	Any rust				

4. Flexible Film Connector (FFC)

Defect	Insp	ection Item	Inspection Standards		
Minor	Tilted soldering		Within the angle +5°	Acceptable	
Minor	Uneven s	older joint /bump		Reject	
			Expose the conductive line	Reject	
Minor	Hole	$\Phi = \frac{L + W}{2}$	Ф > 1.0mm	Reject	
Minor	Y-V-	sition shift	Y > 1/3D	Reject	
WIIIIOI	- X - - 	₹	X > 1/2Z	Reject	

5. Screw

Defect Inspection Item		Inspection Standards	
Major	Screw missing/loosen		Reject
Minor	Screw oxidation	Any rust	Reject
Minor	Screw deformation	Difficult to accept screw driver	Reject

6. Heatseal 、TCP 、FPC

Defect	Inspection Item	Inspection Standards	
Major	Scratch expose conductive layer		Reject
Minor	HS Hole $\Phi = \frac{L + W}{2}$	Φ> 0.5mm	Reject
Major	Adhesion strength	Less than the specification	Reject
Minor	Position shift	Y > 1/3D	Reject
IVIII IOI	T X	X > 1/2Z	Reject
Major	Conductive line break		Reject

7. LED Backing Protective Film and Others

Defect	Inspection Item	Inspection Standards				
		Acceptable number of units				
Minor		⊕ <u><</u> 0.10mm	ignore			
		0.10<⊕ <u><</u> 0.15mm	2			
	LED dirty, prick	0.15<⊕ <u><</u> 0.2mm	1			
		Φ>0.2mm	0			
		The distance between any two spots should be ≥ Any spot/dot/void outside of viewing area is accept				
Minor	Protective film tilt	Not fully cover LCD	Reject			
Major	COG coating	Not fully cover ITO circuit	Reject			

8. Electric Inspection

b. Liectric inspection									
Defect	Inspection Item	Inspection Standards							
Major	Short		Reject						
Major	Open		Reject						

9. Inspection Specification of LCD

Defect	ection Specific	ect Item		In	spection	n St	andards	5	
		* Glass Scratch	W		<u><</u> 0.03		0.05 <u>0</u>	5 V	V>0.05
		* Polarizer Scratch	L	I	_<5		L<3		Any
Minor	Linear Defect	* Fiber and Linear	ACC. NO.	1			1 1		Reject
		material	Note	L is the length and W is the width of the defec				efect	
		* Foreign material		Φ <u><</u> 0.1	0.1<⊕ <u><</u> 0).15 ().15<⊕ <u><</u> 0	.2	Φ>0.2
	Black Spot and	between glass and polarizer or glass		3EA / 100mm²	2		1		0
Minor	Polarizer Pricked	and glass * Polarizer hole or protuberance by external force	Note		$\boldsymbol{\Phi}$ is the average diameter of the defect. Distance between two defects > 10mm.				
		* Unobvious	Φ	Φ<	<u><</u> 0.3	0.3	<⊕ <u><</u> 0.5	0.	5<⊕
	White Spot	transparent foreign material between	ACC. NO.	3EA / 1	100mm ²		1		0
Minor	and Bubble in polarizer	glass and glass or glass and polarizer * Air protuberance between polarizer and glass	Note	Φ is the average diameter of the defect. Distance between two defects > 10mm.					
			Φ	Φ <u><</u> 0.10	0.10<⊕≤	0.10<⊕ <u><</u> 0.20		.20<⊕ <u><</u> 0.25	
		W 1	ACC. NO.	3EA / 100mm²	2	2		1	
Minor	Segment Defect	1 - W - L		W is more	e than 1/2 s	segme	nt width		Reject
	20.00		Note	dote $\Phi = \frac{L + W}{2}$ Distance between two defect is 10mm					
			Φ	Φ <u><</u> 0.10	0.10<⊕≤	0.20	0.20<⊕≤	0.25	Φ>0.25
	Protuberant	w W	W	Glue	W <u><</u> 1/2 \$ W <u><</u> 0.		W <u><</u> 1/2 · W <u><</u> 0.		Ignore
Minor	Segment	$\Phi = (L + W)/2$	ACC. NO.	3EA / 100mm²	2		1		0
			1. Seg	ment					
			Е		_		3 <u><</u> 1.0mm		I.0mm
Minor	Assembly		B-		-A<1/2B		A<0.2		<0.25
Minor	Mis-alignment		Jud				eptable	eptable Acceptable	
			2. Dot	Matrix					1
			Deformation>2° Reju				Reject		
Minor	Stain on LCD Panel Surface		Accept when stains can be wiped lightly with a soft cloth or a similar one. Otherwise, judged according to the above items: "Black spot" and "White Spot"						

14/17 **Model No.:** EC1602K3FVW7B-B0 **Ver:1**.0

9. RELIABILITY

NO.	Item	Condition	Criterion		
1	High Temperature Operating	70°C, 96Hrs			
2	Low Temperature Operating	-20℃, 96Hrs			
3	High Humidity	50°C, 90%RH, 96Hrs			
4	High Temperature Storage	80°C, 96Hrs			
5	Low Temperature Storage	-30℃, 96Hrs	No defect in cosmetic and operational functi		
		Random wave	on allowable.		
6	Vibration	10 ~ 100Hz	Total current Consumption should be below doub		
	Acceleration: 2g		le of initial value.		
		2 Hrs per direction(X,Y,Z)			
		-20°C to 25°C to 70°C			
7	Thermal Shock	(60Min) (5Min) (60Min)			
		16Cycles			
	505 T .:	Contract Discharge Voltage: +1 ~ 5kV and -1 ~ -5kV	There will be discharged ten times		
8	ESD Testing	Air Discharge Voltage: +1 ~ 8kV and -1 ~ -8kV	at every discharging voltage cycle. The voltage gap is 1kV.		

Note: 1) Above conditions are suitable for our company standard products.

²⁾ For restrict products, the test conditions listed as above must be revised.

10. HANDLING PRECAUTION

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers, which easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

(2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Tricolor trifler thane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface. Do not use the following solvent:

- Water
- Kenton
- Aromatics
- (3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

(4) Packaging

- Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.
- To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.

(5) Caution for operation

- It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.
- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's .which will come back in the specified operating temperature range.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- -A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the relative condition of 40°C, 50%RH or less is required.

(6) Storage

In the case of storing for a long period of time, (For years) for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)

(7) Safety

- It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol. Which should be burned up later. When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

11. OUTLINE DIMENSION

